SCLS418G - JUNE 1998 - REVISED JULY 2003

- Inputs Are TTL-Voltage Compatible
- True Outputs
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

description/ordering information

The 'AHCT367 devices are designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. These devices are organized as dual 4-line and 2-line buffers/drivers with active-low output-enable (1OE and 2OE) inputs. When OE is low, the device passes noninverted data from the A inputs to the Y outputs. When OE is high, the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, $\overline{\text{OE}}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

SN54AHCT367 J OR W PACKAGE
SN74AHCT367 D, DB, DGV, N, NS, OR PW PACKAGE
(TOP VIEW)

	(,	
1OE 1A1 1Y1 1A2 1Y2 1A3 1Y3 GND	6 7	σ	14 13 12] V <u>cc</u>] 2OE] 2A2] 2Y2] 2A1] 2Y1] 2Y1] 1A4] 1Y4

SN54AHCT367 . . . FK PACKAGE (TOP VIEW)

	101 NC	Vcc 20E	
			1
1Y1 1A2 NC 1Y2 1A3	3 2 1	^{20 19} 18	2A2 2Y2
1A2	5	17	2Y2
NC		16	NC
1Y2	7	15	2A1 2Y1
1A3	8	14	2Y1
	NC 13	44 A4	

NC - No internal connection

TA	PACK	AGE [†]	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube	SN74AHCT367N	SN74AHCT367N
	SOIC - D	Tube	SN74AHCT367D	AHCT367
	3010 - 0	Tape and reel	SN74AHCT367DR	AHC1307
–40°C to 85°C	SOP – NS	Tape and reel	SN74AHCT367NSR	AHCT367
-40°C 10 85°C	SSOP – DB	Tape and reel	SN74AHCT367DBR	HB367
	TSSOP – PW	Tube	SN74AHCT367PW	HB367
	1330F - FW	Tape and reel	SN74AHCT367PWR	прэ07
	TVSOP – DGV	Tape and reel	SN74AHCT367DGVR	HB367
	CDIP – J	Tube	SNJ54AHCT367J	SNJ54AHCT367J
–55°C to 125°C	CFP – W	Tube	SNJ54AHCT367W	SNJ54AHCT367W
	LCCC – FK	Tube	SNJ54AHCT367FK	SNJ54AHCT367FK

ORDERING INFORMATION

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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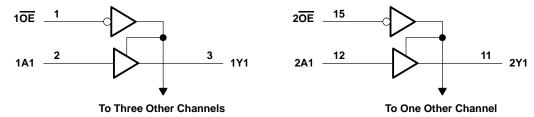


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FUNCTION TABLE (each buffer/driver)								
INP	JTS	OUTPUT						
OE	Α	Y						
Н	Х	Z						
L	Н	н						
L	L	L						

logic diagram (positive logic)



Pin numbers shown are for the D, DB, DGV, J, N, NS, PW, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC} Input voltage range, V_I (see Note 1) Output voltage range, V_O (see Note 1) Input clamp current, I_{IK} ($V_I < 0$) Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$ Continuous output current, I_O ($V_O = 0$ to V_{CC}) Continuous current through V_{CC} or GND Package thermal impedance, θ_{JA} (see Note 2)	c)	$\begin{array}{cccc} -0.5 \ V \ to \ 7 \ V \\ -0.5 \ V \ to \ V_{CC} + 0.5 \ V \\ -20 \ mA \\ \pm 20 \ mA \\ \pm 25 \ mA \\ \pm 25 \ mA \\ \pm 75 \ mA \\ 73^{\circ}C/W \\ 82^{\circ}C/W \\ 82^{\circ}C/W \\ 120^{\circ}C/W \\ 67^{\circ}C/W \\ 64^{\circ}C/W \end{array}$
Storage temperature range, T _{stg}		

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.



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recommended operating conditions (see Note 3)

		SN54AH	SN54AHCT367		SN74AHCT367		
		MIN	MAX	MIN	MAX	UNIT	
VCC	Supply voltage	4.5	5.5	4.5	5.5	V	
VIH	High-level input voltage	2	h	2		V	
VIL	Low-level input voltage		0.8		0.8	V	
VI	Input voltage	0	5.5	0	5.5	V	
Vo	Output voltage	0	VCC	0	VCC	V	
ЮН	High-level output current	20	-8		-8	mA	
IOL	Low-level output current	201	8		8	mA	
$\Delta t/\Delta v$	Input transition rise or fall rate	9	20		20	ns/V	
TA	Operating free-air temperature	-55	125	-40	85	°C	

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	Vee	Т	₄ = 25°C	;	SN54AH	ICT367	SN74AH	CT367	UNIT
PARAMETER	TEST CONDITIONS	Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
Veu	I _{OH} = -50 μA	4.5 V	4.4	4.5		4.4		4.4		V
VOH	I _{OH} = -8 mA	4.5 V	3.94			3.8		3.8		v
VOL	I _{OL} = 50 μA	4.5 V			0.1		0.1		0.1	V
VOL	I _{OL} = 8 mA	4.5 V			0.36		0.44		0.44	v
կ	$V_{I} = 5.5 V \text{ or GND}$	0 V to 5.5 V			±0.1*		±1*		±1	μΑ
loz	$V_I = V_{CC}$ or GND, $V_O = V_{CC}$ or GND, $\overline{OE} = V_{IH}$	5.5 V			±0.25	CY D	±2.5		±2.5	μΑ
ICC	$V_{I} = V_{CC} \text{ or } GND, \qquad I_{O} = 0$	5.5 V			4	201	40		40	μA
∆lCC [†]	One input at 3.4 V, Other inputs at V_{CC} or GND	5.5 V			1.35	NHd	1.5		1.5	mA
Ci	$V_I = V_{CC}$ or GND	5 V		2.5	10		10		10	pF
Co	$V_{O} = V_{CC} \text{ or GND}$	5 V		5						pF

* On products compliant to MIL-PRF-38535, this parameter is not production tested at V_{CC} = 0 V.

[†] This is the increase in supply current for each input at one of the specified TTL voltage levels, rather than 0 V or V_{CC}.



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switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

00				-							
PARAMETER	FROM	то	LOAD	Тд	∖ = 25°C	;	SN54AH	CT367	SN74AH	CT367	UNIT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
^t PLH	А	Y	C _I = 15 pF		2.5*	4.8*	1*	6.5*	1	5.5	ns
^t PHL	A	T			2.5*	4.8*	1*	6.5*	1	5.5	115
^t PZH	OE	Y	Ci = 15 pE		3.5*	8*	1*	9.5*	1	8.5	ns
^t PZL	ÛE	T	C _L = 15 pF		2.8*	7*	1*	8.5*	1	7.5	115
^t PHZ	OE	Y	C _L = 15 pF		3.1*	8*	1*	9.5*	1	8.5	-
^t PLZ	ÛE	I			2.8*	7*	1*	8.5*	1	7.5	ns
^t PLH	А	Y	C ₁ = 50 pF		3.5	5.8	Ð,	7.5	1	6.5	ns
^t PHL	A		CL = 30 pr		3.3	5.8	00	7.5	1	6.5	115
^t PZH	OE	Y	C _L = 50 pF		4.5	9	4	10.5	1	9.5	ns
^t PZL	ÛE	I	CL = 30 pr		3.7	8	1	9.5	1	8.5	115
^t PHZ	OE	Y	C _L = 50 pF		4.1	9	1	10.5	1	9.5	ns
^t PLZ	UL	r	CL = 50 pr		3.6	8	1	9.5	1	8.5	115

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

noise characteristics, V_{CC} = 5 V, C_L = 50 pF, T_A = 25°C (see Note 4)

	PARAMETER	SN7	UNIT		
		MIN	TYP	MAX	UNIT
V _{OL(P)}	Quiet output, maximum dynamic V _{OL}		0.4		V
V _{OL(V)}	Quiet output, minimum dynamic V _{OL}		-0.4		V
VOH(V)	Quiet output, minimum dynamic V _{OH}		4.7		V
VIH(D)	High-level dynamic input voltage	2			V
V _{IL(D)}	Low-level dynamic input voltage			0.8	V

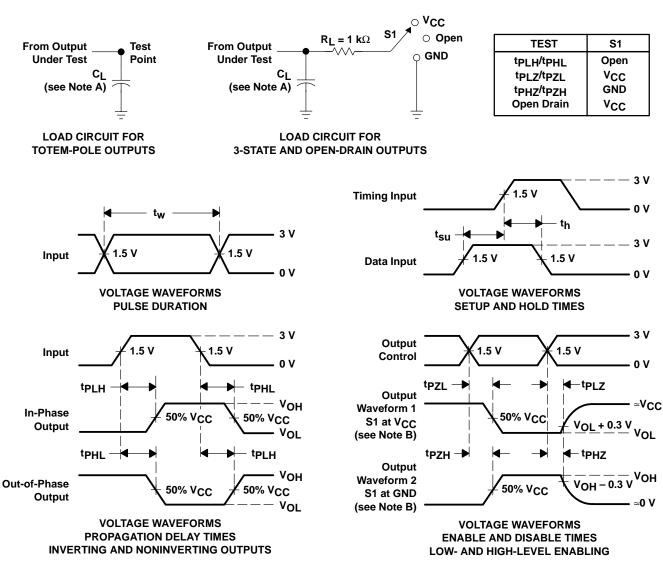
NOTE 4: Characteristics are for surface-mount packages only.

operating characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd} Power dissipation capacitance	No load, f = 1 MHz	22	pF



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PARAMETER MEASUREMENT INFORMATION

NOTES: A. C₁ includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_r \leq 3 ns, t_f \leq 3 ns.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	n MSL Peak Temp ⁽³⁾
SN74AHCT367D	ACTIVE	SOIC	D	16	40	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74AHCT367DBR	ACTIVE	SSOP	DB	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74AHCT367DGVR	ACTIVE	TVSOP	DGV	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74AHCT367DR	ACTIVE	SOIC	D	16	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74AHCT367N	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74AHCT367NSR	ACTIVE	SO	NS	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74AHCT367PW	ACTIVE	TSSOP	PW	16	90	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74AHCT367PWR	ACTIVE	TSSOP	PW	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

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N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



PLASTIC SMALL-OUTLINE

MPDS006C - FEBRUARY 1996 - REVISED AUGUST 2000

DGV (R-PDSO-G**)

24 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

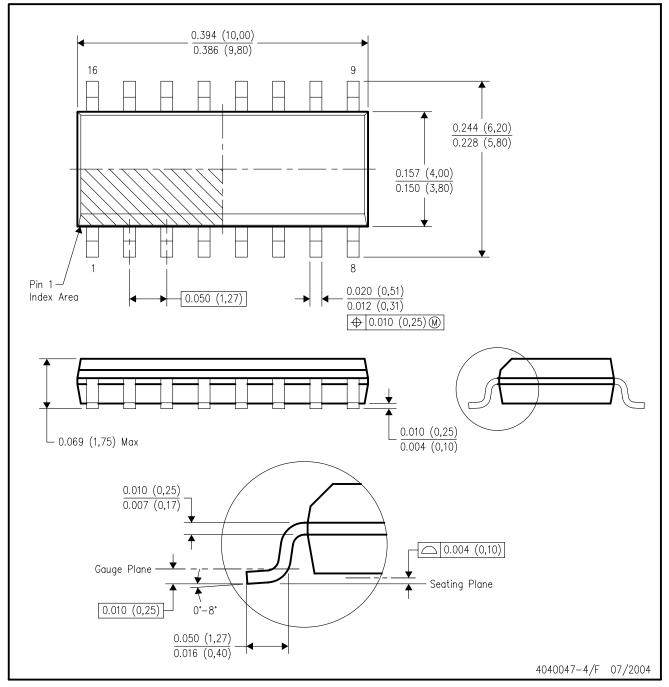
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
- D. Falls within JEDEC: 24/48 Pins MO-153

14/16/20/56 Pins – MO-194



D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012 variation AC.



PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



MSSO002E - JANUARY 1995 - REVISED DECEMBER 2001

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-150



MTSS001C - JANUARY 1995 - REVISED FEBRUARY 1999

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



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